

UNIVERSAL LOGIC CIRCUIT (ULC)(tm) DEVICES

August 1989

T-42-11-09

FEATURES

- Factory-customized pin- and function-compatible replacements for field-programmable PAL^(Im), GAL^(Im), FPLA, and FPLS devices, and other PLDs
- Completely turnkey conversion to ULC devices using ABEL^(tm) design files and two samples of the fieldprogrammed PLD
 - MDS completes conversion and develops test vectors using automatic tools
 - Factory-customized ULC devices shipped fully marked and tested
- 25-50% cost-reduction from ULC devices compared to fieldprogrammable devices
 - Highly compacted dice due to efficient architecture and sub-micron technology
 - Up to 25% cost-reduction for slower (15ns) PAL/GAL/FPLA/ FPLS devices
 - Up to 50% and even higher cost-reduction high-speed (10/ 12ns) PAL/GAL devices and larger PLDs

Quality improvement

- Each ULC device tested for functional, DC and AC specifications
- Target PPM level of 100 compared to 5,000-10,000 PPM for one-time field programmable devices
- Saves time on expensive board rework possibly needed with partially tested field-programmable devices
- Eliminates need for sockets used in production boards to make above rework easy
- Power consumption reduction
 - ULC device power consumption roughly 5-15mA
 - Cuts power to 5-10% of bipolar field-programmable devices and 10-15% of CMOS devices
- Simpler manufacturing
 - Eliminates need for in-house programming, testing or labeling, saving an additional 20-25%
 - Reduces manufacturing costs and leadtime

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TABLE OF CONTENTS

		Page
1.	OVERVIEW	. 4
2.	BENEFITS OF ULC DEVICES	4
	2.1 Cost Reduction	4
	2.2 Quality Improvement	4
	2.3 Power Consumption Reduction	4
	2.4 Simpler Manufacturing	5
3.	DESIGN FLOW	5
	3.1 Boolean Eqaution Conversion	5 5
	3.2 Test Program Generation and Verification	5
	3.3 ULC Device Generation	5
	3.4 Testing of ULC Devices	5
4.	TECHNOLOGY	6
5.	FIELD-PROGRAMMABLE DEVICES SUPPORTED	-
	5.1 Architecture	7
	5.2 Speed	7
	5.3 Packages	. 8
_		8
6.	TESTING ULC DEVICES	8
7.	ELECTRICAL SPECIFICATIONS	9
	7.1 Maximum Ratings	9
	7.2 Operating Limits	9
8.	ORDERING INFORMATION	10
	8.1 Part Numbers	10
	8.2 Leadtimes	10
	8.3 How to Order	10

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1. OVERVIEW

Programmable logic is an excellent tool for design development. In production, where cost, quality, power consumption, and programming overhead are important considerations, Matra Design Semiconductor (MDS) offers ULC (Im) devices as a preferable alternative to PAL^(R) devices, GAL^(R) devices, FPLAs, FPLSs, and other PLDs.

ULC (Universal Logic Circuit) devices are

factory-customized circuits that implement pinand function-compatible replacements for field-programmable logic devices. Devices that can be replaced on a completely turnkey basis without customer engineering involvement are listed in Section 5. Other PLDs can also be supported, but may require customer engineering support. Among PAL and GAL devices, FPLAs and FPLSs, MDS focuses on 10 and 15ns devices.

2. BENEFITS OF ULC DEVICES

2.1 Cost Reduction

With highly compacted dice, a high-yielding manufacturing technology, and sub-micron feature sizes, ULC devices use significantly less silicon per gate than field-programmable devices. The resulting cost-reduction, including mask- and prototype-making costs, ranges between 25% for slower (15ns) PAL devices to 50% and even higher for high-speed (12/ 10ns) PAL devices and larger PLDs.

2.2 Quality Improvement

One-time field-programmable devices are tested only partially since complete verification requires programming. As a result, one-time field-programmable devices exhibit high ppm levels in the range of 5,000-10,000 ppm.

MDS ULC devices are built to meet 100 ppm levels. They are 100% tested at the wafer and package levels at the factory. See section 6 on 'Testing'.

Further, most field-programmable devices are typically tested after programming only for correct programming (fuse map verification), which does not necessarily guarantee correct operation. Any functional testing performed is typically basic due to (i) the limited testing capability of the programming environments, and (ii) the limited number of test patterns

typically generated to perform the tests. Limited testing of the nature described above makes boards manufactured with these devices susceptible to failure at final test. This reduces manufacturing yield of the board or system, and raises product cost, or requires extra time, money, labor and materials for rework. This also reduces manufacturing thruput.

MDS ULC devices are tested with more extensive tests generated with automatic test vector generation software. (See section 3 for design flow.) The software develops patterns to achieve a high degree of test coverage, or in other words, ensures that the circuit is substantially exercised in the testing process. Coupled with the fact that each device is tested at least twice before leaving the MDS factory, this reduces failure rates to less than 1 in 10,000 (100 ppm).

This difference is significant to systems manufacturers for improving system yields, manufacturing cost and manufacturing thruput - factors that are especially important in volume markets.

2.3 Power Consumption Reduction

The power consumption for bipolar PAL

19E D

devices is rated around 150-200mA, and for CMOS PAL/GAL devices around 75-100mA. ULC power consumption, although a strong function of device clock rates, typically lies between 5-15mA. This cuts power by a factor of 10-15 compared to bipolar field-programmable devices, and by a factor of 5-10 compared to CMOS field-programmable devices. Further, this is accomplished without putting the device in a standby mode, and thus without the latencies and extra logic associated with

standby operation.

2.4 Simpler Manufacturing

Elimination of need for in-house programming. testing or labeling, reduces cost by an additional 20-25%. Elimination of sockets in environments where the field-programmed devices are not tested prior to placement on the board, can save another 5-10%.

3. DESIGN FLOW

MDS uses the ABEL(tm) PLD design language as its preferred input format. MDS uses proprietary software to perform logic reduction and translation, and for functional and timing verification of the translated database. The verified final database is used to generate the factory-programmed parts and the test programs for manufacturing test. The logic translation and test generation are done automatically by MDS engineers, eliminating the need for the customer to spend any engineering effort in most cases. This reduces the customer effort needed for the conversion to the same as that needed for working with the local programming and test service bureau, distributor, or in-house production programming organization. At the same time, the cost, quality, and power consumption of ULC devices is superior to the field-programmed alternatives.

Figure 3-1 on the next page shows the steps executed in the conversion process. The steps are described in further detail below.

3.1 Boolean Equation Conversion

ABEL-format equations are converted to the programming database using automatic

conversion software.

3.2 Test Program Generation and Verifica-

The converted database is used to generate the test vectors. These test vectors are verified for correctness by running them against one or two programmed samples of the field-programmed device. This process also indirectly verifies the correctness of the conversion.

3.3 Programmed Device Generation

With the converted design verified, MDS processes the programming data to build the factory-programmed devices.

3.4 Testing of Programmed Devices

The programmed devices are tested for functional, DC and AC specifications at the wafer sort and final test level. See section on Testing.

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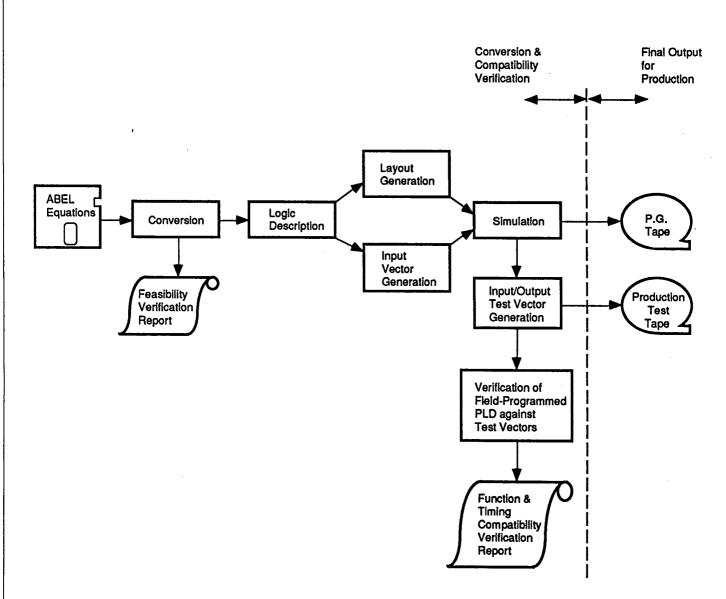


Figure 3-1: Automatic PAL/GAL/FPLS/FPLA/PLD Device Replacement Flow

4. TECHNOLOGY

MDS uses advanced sub-micron CMOS technology in its ULC devices. The n-transistor channel lengths are sized at 0.8-microns (drawn). This technology offers toggle rates in excess of 200 MHz and system clock rates in excess of 125MHz. The technology is also

designed for cost-effective volume production. and thus offers state-of-the-art performance combined with highly predictable and costeffective manufacturability. ULC devices using this technology has been in production since late 1988.

5. FIELD PROGRAMMABLE DEVICES SUPPORTED

5.1 Architectures

The following chart shows the PAL/PLD devices MDS can replace with ULC devices on a completely turnkey basis:

ULC20	ULC24	ULC28	ULC40
Devices	Devices	Devices	Devices
GAL16V8 PAL18P8 PAL16P8 PAL16L8 PAL10L8 PAL12L6 PAL14L4 PAL16L2 PAL23S8 PAL16RP8 PAL16RP6 PAL16R8 PAL16R8 PAL16R6 PAL16R4 PLS151 PLC153 PLS153 PLS153 PLS153 PLS155 PLS157 PLS155 PLS157 PLS159 EP310 EP320	GAL20V8 GAL39V18 PAL29M16 PAL32VX10 PAL22V10 PAL22RX8 PAL20RS10 PAL20RS8 PAL20RS4 PAL20X10 PAL20X8 PAL20X4 PAL20RP10 PAL20RP6 PAL20RP6 PAL20RP6 PAL20RP6 PAL20RB PAL20	PLS100 PLS101 PLS103 PLS105 PLUS405	PAL32R16 EP900 EP910 EP1200

5.2 Speeds

The following table shows the standard speed versions of various PLDs supported:

PLD	Speed Versions Supported		
PAL Devices	10ns, 12ns, 15ns, 25ns		
GAL Devices	10ns, 12ns, 15ns, 20ns, 25ns		
FPLAs/ FPLSs	12ns, 15ns, 20ns, 22ns, 25ns		
Other PLDs	All speeds		

MDS can also support other speeds not available as standard selections in field-programmable devices, at a slightly higher cost. For example, 10-ns 22V10s can be supported, even though field programmable versions that run as fast are not available.

7.5ns ULC devices are expected to be available in Q1 '90.

5.3 Packages

MDS provides the ULC devices in packages compatible and equivalent to those used for the field-programmable devices. This includes plastic DIPs, skinny DIPs, PLCCs, quad flatpaks, and ceramic DIP/CERDIP equivalents as available. Windowed packages are substituted by windowless equivalents.

6. TESTING ULC DEVICES

Each ULC device is tested twice after it has been programmed, before it is shipped to a customer. The first set of tests, consisting of DC and functional tests, are done on each device after programming and prior to packaging. The second and final set, consisting of functional, DC and AC tests, are done on each device after packaging. Re-testing, consisting of functional, DC and AC tests, is also done for quality assurance on a lot sampling basis.

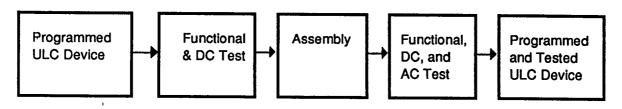


Figure 6-1: Flow diagram for testing customized ULC devices

7. ELECTRICAL SPECIFICATIONS

7.1 Maximum Ratings

V_{DD} level with reference to V_{SS} Minimum voltage on any other pin Maximum voltage on any other pin Storage temperature Static discharge voltage (per Mil Std 883 Method 3015)

-0.5 to +6.5V

-0.5V

VCC + 0.5V

-65 deg C to +110 deg C.

>2000V

7.2.1 Operating Limits (0 to 70 deg C, $5V \pm 10\%$)

7.3 D.C. Characteristics

Para- meter	Description	Min	Max	Unit	Test Conditions
V _{OH}	Output HIGH Voltage	2.4		V	I _{OH} = -24mA
Vol	Output LOW Voltage		0.5	v	l _{oL} = 24mA
V _{IH}	Input HIGH Voltage	2.0		v	•
V _{IL}	Input LOW Voltage		0.8	v	
I _{IX}	Input Leakage Current	-10	+10	υA	V _{ss} <v<sub>iN<v<sub>cc</v<sub></v<sub>
l _{oz}	Output Leakage Current	-40	+40	uA	V _{ss} <v<sub>our<v<sub>cc</v<sub></v<sub>
· I _{CSB}	Standby Current		5	mA	V _{cc} = Max; V _{iN} = GND; Outputs open
I _{cc}	Power Supply Current		6	mA	V _{CC} = Max; V _{IN} = GND; Outputs Open; F _{op} = 1MHz (1)

Note

1. Measured at $F_{op} = 1$ MHz.

7.2.2 A.C. Characteristics ($T_{CASE} = 0 \text{ deg C to } +70 \text{ deg C}$; $V_{CC} = 5V + 5\%$)

All A.C. parameters are guaranteed to be equal to or better than the field-programmable devices being replaced.

8. ORDERING INFORMATION

8.1 Part Number

ULCXX XXXXXXXXXXXXXXXXXX

Mask-Programmed Complete Part Number of Field-Programmable

Universal

Device, including

Logic

Manufacturer prefix, device, part number, speed, package, and

Device temperature range

For an example, see figure 8-1 below. If you use more than one vendor manufacturer of the field programmable device, please specify the manufacturer offering the more stringent specification, if there is a difference. If there is no difference, vendor identification is optional.

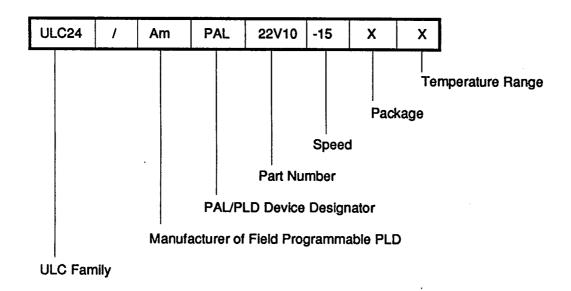


Figure 8-1: Example part number for replacement of a 15ns 22V10 in a 24-pin PDIP

8.2 Leadtimes

From the time that a customer provides the ABEL boolean equations describing the fieldprogrammable device configuration, along with 2-3 programmed samples, MDS uses automatic software to convert the equations to the ULC device configuration and test data, and delivers fully compatible samples six weeks later. Small pre-production quantities

can also be delivered at the same time. First production parts are available four weeks later.

8.3 How to Order

To submit a code and place an order, contact your local MDS representative or MDS headquarters at 800-338-GATE.